L Number	Hits	Search Text	DB	Time stamp
-	150	(73/204.22).CCLS.	USPAT;	2003/02/26 15:59
		("18 and semiconductor").PN.	US-PGPUB;	
		TANKARI F CODY	EPO; JPO	
-	0	("18 and semiconductor").PN.	USPAT;	2002/09/30 14:01
			US-PGPUB;	
			EPO; JPO	
-	24	((73/204.22).CCLS.) and semiconductor	USPAT;	2002/09/30 14:02
			US-PGPUB;	
	•		EPO; JPO	
-	16	(((73/204.22).CCLS.) and semiconductor) and (seal\$4 ring)	USPAT;	2002/09/30 14:03
			US-PGPUB;	
			EPO; JPO	
_	15	(((((73/204.22).CCLS.) and semiconductor) and (seal\$4 ring)) and	USPAT;	2002/09/30 14:05
		(housing enclosure body fixture)	US-PGPUB;	
		(nousing enclosure body minute)	EPO; JPO	
	1	("6351390").PN.	USPAT;	2002/09/30 15:07
-	•	(0551570).114.	US-PGPUB;	
			EPO; JPO	
	10713	1161	USPAT;	2002/09/30 18:27
-	10713	"flow sensor"	US-PGPUB;	2002/09/30 10.27
			1	1
			EPO; JPO	2002/00/20 15:07
-	2660	"flow sensor" and housing	USPAT;	2002/09/30 15:07
			US-PGPUB;	
			EPO; JPO	
-	6	(("flow sensor" and housing) and semiconductor) and (seal\$4 ring) near4	USPAT;	2002/09/30 15:30
İ		semiconductor	US-PGPUB;	
İ			EPO; JPO	
- 1	0	20020043710.URPN.	USPAT	2002/09/30 15:08
_	0	5871627.URPN.	USPAT	2002/09/30 15:12
_	0	5871627.URPN.	USPAT	2002/09/30 15:12
_ !	3277	"strip conductor"	USPAT;	2002/09/30 15:31
-	3211	Strip conductor	US-PGPUB;	
			EPO; JPO	
	7	("strip conductor" and 73/\$7.ccls.) and semiconductor	USPAT;	2002/09/30 16:19
-	,	(Strip conductor and 151\$1.ccis.) and semiconductor	US-PGPUB;	2002/03/20 10:13
			EPO; JPO	
	52	"strip conductor" and 73/\$7.ccls.	USPAT;	2002/09/30 17:49
-	32	Strip conductor and 757\$7.ccis.	US-PGPUB;	2002/05/30 17:45
			EPO; JPO	
	26	(U 4 1 1 4 4 U 4 4 7 2 / 671 -) and amount?	(2002/09/30 17:49
-	36	("strip conductor" and 73/\$7.ccls.) and spac\$3	USPAT;	2002/09/30 17.49
			US-PGPUB;	
			EPO; JPO	
-	19	(("strip conductor" and 73/\$7.ccls.) and spac\$3) and force	USPAT;	2002/09/30 17:49
			US-PGPUB;	-
			EPO; JPO	
-	39	(("flow sensor" and housing) and semiconductor) and (glue paste)	USPAT;	2002/09/30 17:56
			US-PGPUB;	
			EPO; JPO	
_	102	("flow sensor" and housing) and (ridg\$3 bump tip) near4 (housing	USPAT;	2002/09/30 18:29
		enclosure chamber body plate mount\$4)	US-PGPUB;	
		Choicean chamber coay plane incame iy	EPO; JPO	
_	26	(("flow sensor" and housing) and (ridg\$3 bump tip) near4 (housing	USPAT;	2002/09/30 18:29
-	20	enclosure chamber body plate mount\$4)) and (semiconductor silicon)	US-PGPUB;	
		eliciosure chamber body prate mounts+)) and (semiconductor smeon)	EPO; JPO	
	177	("flow concor" and housing) and comisanductor	USPAT;	2002/09/30 18:52
-	377	("flow sensor" and housing) and semiconductor	US-PGPUB;	2002/09/30 10.32
			EPO; JPO	2002/02/2015
•	942	(73/202,204.15,204.16,204.22,204.26).CCLS.	USPAT;	2003/02/26 15:59
			US-PGPUB;	
			EPO; JPO	
	2	(((73/202,204.15,204.16,204.22,204.26).CCLS.) and "semiconductor	USPAT;	2003/02/26 16:02
	_	chip") and (seal\$5 O) near3 ring	US-PGPUB;	
			EPO; JPO	I

	_	
((73/202,204.15,204.16,204.22,204.26).CCLS.) and "semiconductor	USPAT;	2003/02/27 09:42
chip"	US-PGPUB;	
	EPO; JPO	
(((73/202,204.15,204.16,204.22,204.26).CCLS.) and "semiconductor	USPAT;	2003/02/27 11:08
chip") and seal\$4	US-PGPUB;	
• /	EPO; JPO	
("4548078").PN.	USPAT;	2003/02/27 11:08

US-PGPUB; EPO; JPO

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